

Title (en)  
SINTERED TUNGSTEN ALLOY

Title (de)  
GESINTERTE WOLFRAMLEGIERUNG

Title (fr)  
ALLIAGE DE TUNGSTÈNE FRITTÉ

Publication  
**EP 2789708 A4 20151014 (EN)**

Application  
**EP 12856450 A 20121127**

Priority  
• JP 2011267845 A 20111207  
• JP 2012080565 W 20121127

Abstract (en)  
[origin: EP2789708A1] There is provided a flat plate-like sintered tungsten alloy that can be molded into a complex shape by press working or forge processing. The flat plate-like sintered tungsten alloy contains 85% by mass or more and 98% by mass or less of W, 1.4% by mass or more and 11% by mass or less of Ni, and 0.6% by mass or more and 6% by mass or less of at least one substance selected from the group consisting of Fe, Cu and Co, wherein an elongation percentage of the flat plate-like sintered tungsten alloy in a planar direction is 20% or more.

IPC 8 full level  
**C22C 27/04** (2006.01); **B22F 3/24** (2006.01); **C22C 1/04** (2006.01); **C22F 1/00** (2006.01); **C22F 1/18** (2006.01)

CPC (source: EP US)  
**B22F 3/24** (2013.01 - EP US); **B22F 5/006** (2013.01 - EP US); **C22C 1/045** (2013.01 - EP US); **C22C 27/04** (2013.01 - EP US);  
**C22F 1/02** (2013.01 - EP US); **C22F 1/18** (2013.01 - EP US); **Y10T 428/12014** (2015.01 - EP US)

Citation (search report)  
• [A] CN 101230427 A 20080730 - UNIV CENTRAL SOUTH [CN]  
• [A] JANG ET AL: "Study on the solid-phase sintering of the nano-structured heavy tungsten alloy powder", JOURNAL OF ALLOYS AND COMPOUNDS, ELSEVIER SEQUOIA, LAUSANNE, CH, vol. 434-435, 29 March 2007 (2007-03-29), pages 367 - 370, XP022008679, ISSN: 0925-8388, DOI: 10.1016/J.JALLCOM.2006.08.215  
• See references of WO 2013084749A1

Cited by  
EP3229268A4; CN106756379A; RU2623566C1

Designated contracting state (EPC)  
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)  
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DOCDB simple family (application)  
**EP 12856450 A 20121127**; JP 2012080564 W 20121127; JP 2012080565 W 20121127; JP 2013548184 A 20121127; JP 2013548185 A 20121127; US 201214363401 A 20121127